

HBR30150FCA

Schottky Barrier Rectifiers



Voltage: 150 Volts

Current: 30 A

Package: TO-220F

Features

- > NH'S Plane Schottky Barrier Chip Technology
- > Low Forward Voltage Drop For High Efficiency
- > Low Power Loss For High Reliability
- > High Frequency Switching Speed

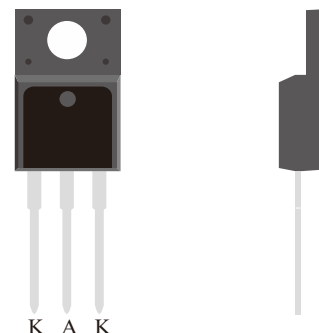
Mechanical Data

- > **Case:** Molded With UL-94 ClassV-0 Recognized, RoHS-Compliant
- > **Polarity:** Look At The Diagram And Polarity On The Right
- > **Terminals:** Tin Plated Leads,Solderable Per J-STD-002 And JESD22-B102

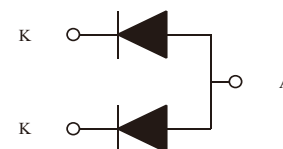
Typical Applications

- > Switch Mode Power Supplies (SMPS)
- > Fast Chargers
- > LED Driver And Monitor Lighting
- > Automotive Electronics And Charging Posts

Diagram:



Polarity:



Single Phase,Half Wave,60Hz,Resistive Or Inductive Load.For Capacitive Load,Derate Current By 20%

Maximum Ratings (Ta=25°C Unless Otherwise Specified)

Parameter	Test Conditions	Symbol	Ratings	Unit
Maximum Repetitive Peak Reverse Voltage		V_{RRM}	150	V
Maximum RMS Voltag		V_{RMS}	105	V
Maximum DC Blocking Voltage		V_{DC}	150	V
Maximum Average Forward Rectified Current(Note2)	Per Diode Total device	$I_{F(AV)}$	15 30	A
Peak Forward Surge Current Per Diode	8.3ms Single Half Sine-wave Superimposed On Rate Load	I_{FSM}	150	A
Current Squared Time Per Diode	$t < 8.3ms$	I^2t	93.4	A ² sec
Maximum Mounting Torque	M3 screw	T_{MM}	1.1	N.m

Electrical Characteristics (Ta=25°C Unless Otherwise Specified)

Parameter	Test Conditions	Symbol	Ratings			Unit
			Min.	Typ.	Max.	
Instaneous Forward Voltage Per Diode	Ta=25°C Ta=110°C If= 15.0 A	V_F	-- --	0.91 0.87	0.95 0.91	V
Maximum DC Reverse Current at Rated DC Blocking Voltage	Ta=25°C , $V_R=V_{RRM}$ Ta=110°C , $V_R=V_{RRM}*80\%$	I_{RRM}	-- --	1 1	5 2	uA mA
Typical Junction Capacitance Per Diode	4 V,1MHz	C_J	--	300	--	pF

Thermal Characteristics (Ta=25°C Unless Otherwise Specified)

Parameter	Test Conditions	Symbol	Ratings	Unit
Operating Junction Temperature Range		T_J	-55 to 175	°C
Storage Temperature Range		T_{STD}	-55 to 175	
Thermal Resistance Junction To Ambient With Steady-State	Still Air Environment With Ta=25°C	$R_{\theta JA}$	62.5	°C/W
Thermal Resistance Junction-Case With Steady-State	Device Mounted On 75mm x 45mm x 2.5mm Alu. Heat.	$R_{\theta JC}$	3.0	

Notes: 1.Pulse Test: 300 Us Pulse Width,1% Duty Cycle

2.Device mounted on 250mm x 250mm x 2.0mm Aluminum Plate Heatsink.

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Typical Characteristics Curves

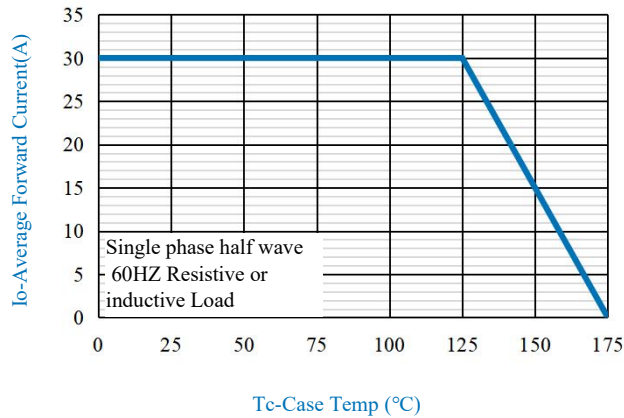


Fig.1-Forward Current Derating Curve

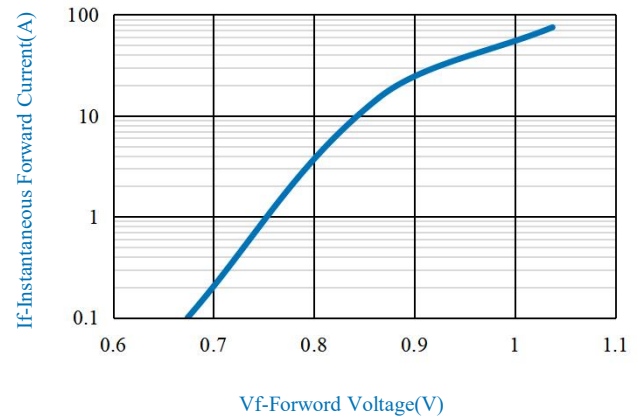


Fig.2-Typical Instantaneous Forward

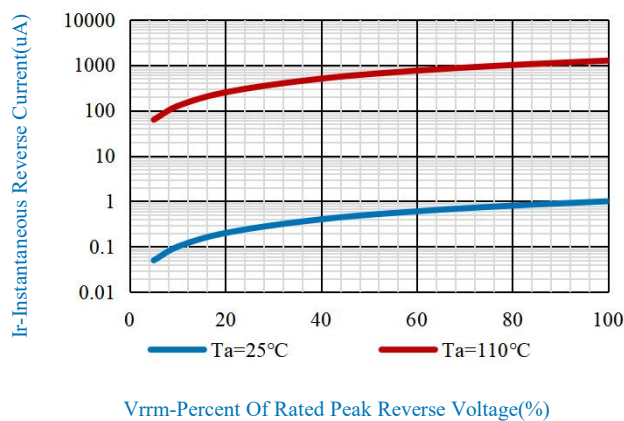


Fig.3-Typical Reverse Characteristics

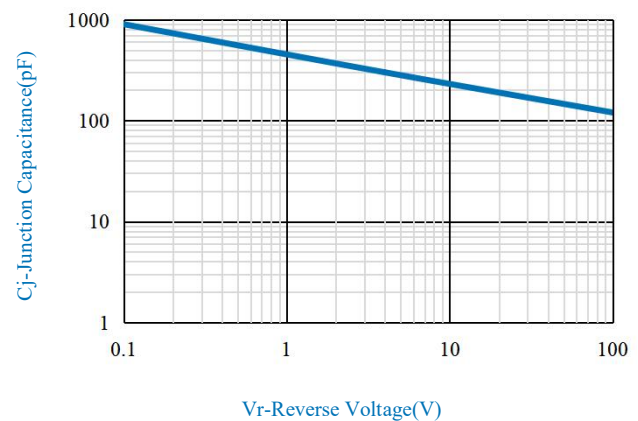


Fig.4-Typical Junction Capacitance

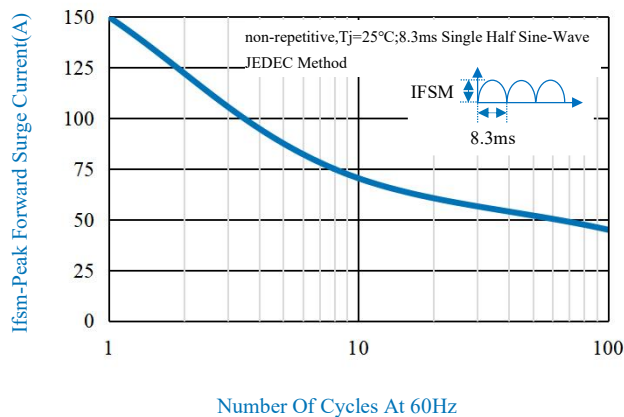


Fig.5-Max. Non-Repetitive Surge Current

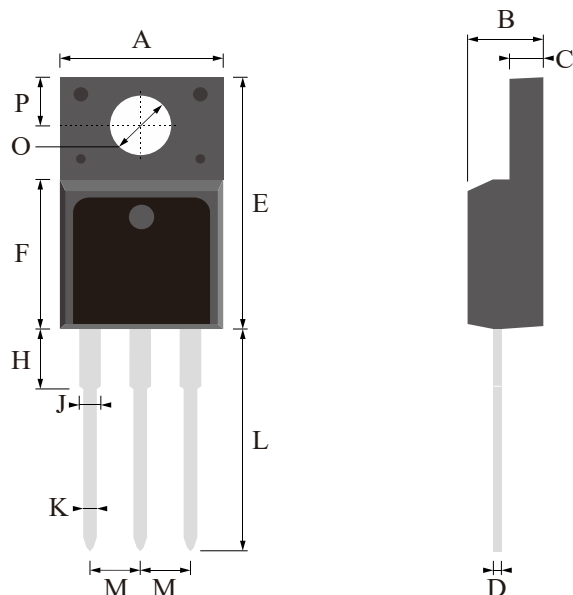
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OUTLINE DRAWINGS

TO-220F

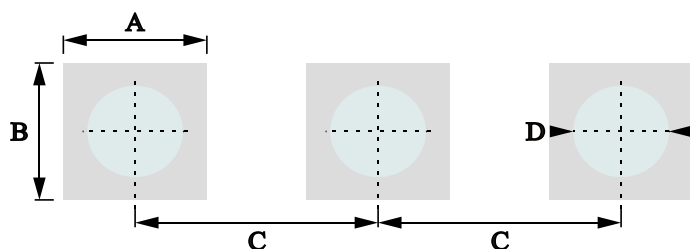


OUTLINE DIMENSIONS

Dim.	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	9.25	-	10.75	0.3642	-	0.4232
B	4.20	-	5.20	0.1654	-	0.2047
C	2.30	-	2.90	0.0906	-	0.1142
D	0.35	-	0.75	0.0138	-	0.0295
E	14.80	-	16.80	0.5827	-	0.6614
F	8.25	-	9.75	0.3248	-	0.3839
L	12.15	-	14.15	0.4783	-	0.5571
H	2.60	-	3.30	0.1024	-	0.1299
J	1.10	-	1.60	0.0433	-	0.0630
K	0.60	-	1.00	0.0236	-	0.0394
M	2.20	-	3.00	0.0866	-	0.1181
O	2.70	-	3.50	0.1063	-	0.1378
P	3.20	-	3.80	0.1260	-	0.1496

RECOMMENDED LAYOUT DRAWINGS

TO-220F



OUTLINE DIMENSIONS

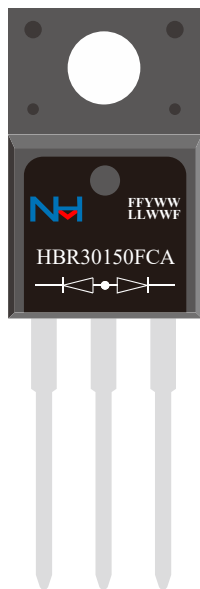
Dim.	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	-	1.60	-	-	0.0630	-
B	-	1.60	-	-	0.0630	-
C	-	2.54	-	-	0.1000	-
D	-	1.00	-	-	0.0394	-

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MARKING



MARKING INSTRUCTION

NH=Niuhan Trademark
FF=Product Line Code,According To Actual Changes
YWW=Date Code,According To Actual Changes
LLWWF=Inernal Code,According To Actual Changes
HBR30150FCA=Model

PACKING INFORMATION

Package Type	Package Code	Product Weight Approx(g/Pcs)	Package Method	Quantity (Pcs/Min. Pack.)	Quantity (Pcs/Inner Box)	Quantity (Pcs/Carton)
TO-220F	P1	2.048	Tube	50	1000	5000

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Recommended wave soldering condition

Product	Peak Temperature	Soldering Time
Pb-free devices	260 +0/-5 °C	5 +1/-1 seconds

Recommended temperature profile for IR reflow

	Profile feature	Sn-Pb eutectic Assembly	Pb-free Assembly
	Average ramp-up rate (TSmax to TP)	3°C/second max.	3°C/second max.
	Preheat-Temperature Min (TS min) -Temperature Max (TS max) -Time(ts min to ts max)	100°C 150°C 60-120 seconds	150°C 200°C 60-180 seconds
	Time maintained above: -Temperature (TL) - Time (tL)	183°C 60-150 seconds	217°C 60-150 seconds
	Peak Temperature(TP)	240 +0/-5 °C	260 +0/-5 °C
	Time within 5°C of actual peak temperature (tp)	10-30 seconds	20-40 seconds
	Ramp down rate	6°C/second max.	6°C/second max.
	Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

Note : All temperatures refer to topside of the package, measured on the package body surface.

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Specification Revision History

Rev.	Date	Changed Items	Pre-Changed Content	Changed Content
A/1	2014-10-20	First Issue		
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